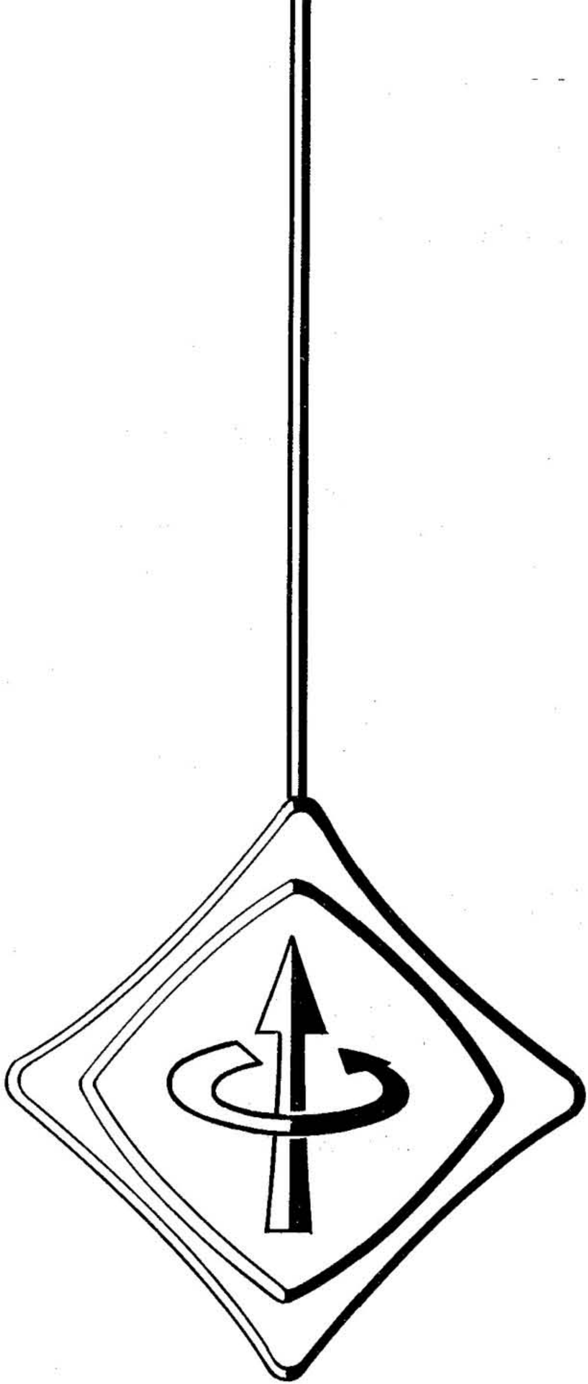

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TABLE OF CONTENTS

KEYNOTE ADDRESS — Dr. George Heilmeier, DoDR&E

"Reliability - Some Early Impressions of a Pentagon Newcomer" 1

NEW AND IMPROVED FAILURE — ANALYSIS TECHNIQUES

Chairman and Organizer: Arnie Lesk

A PROCEDURE FOR THE EVALUATION AND FAILURE ANALYSIS OF MOS MEMORY CIRCUITS USING THE SCANNING ELECTRON MICROSCOPE IN POTENTIAL CONTRAST MODE

S. K. Behera and D. P. Speer 5

THE USE OF CURRENT GAIN AS AN INDICATOR FOR THE FORMATION OF HOT SPOTS DUE TO CURRENT CROWDING IN POWER TRANSISTORS

F. F. Oettinger and S. Rubin 12

SCREENING TECHNIQUES FOR INTERMITTENT SHORTS

R. E. McCullough 19

LASER SCANNING FOR INTEGRATED CIRCUIT TESTING

R. E. McMahon 23

"Prediction of IC and LSI Performance by Specialized Vibration/Detection Test for Presence of Conductive Particles".

B. T. French, J. E. Mann and G. E. Ereckson 26

"A S. E. M. Surface Voltage Measurement Technique".

R. P. Beaulieu, C. D. Cox and T. M. Black 32

DESIGN AND PROCESS CONTROL FOR RELIABILITY, AND MICROWAVE DEVICES

Chairman and Organizer: Jim Cunningham

MOS/LSI CIRCUIT DESIGN: DESIGNING IN RELIABILITY

H. W. Van Beek 36

RELIABILITY IMPROVEMENT BY PROCESS CONTROL

W. H. Schroen, J. G. Aiken, and G. A. Brown 42

AN EXPERIMENTAL MODEL OF THE MICROELECTRONIC ULTRASONIC WIRE BONDING MECHANISM

G. G. Harman and K. O. Leedy 49

RELIABILITY OF MICROWAVE MIXER DIODES

W. J. Moroney and Y. Anand 57

DIAMOND HEAT SINK FOR HIGH RELIABILITY IMPATT

Y. Fukukawa, M. Shinoda, Y. Toyama, M. Yamamoto, S. Yoshioka and K. Kazetani 64

"Reliability Improvement With New Passivation of Solid Encapsulated Transistors".

E. A. Herr 69

RELIABILITY OF PLASTIC — ENCAPSULATED DEVICES

Chairman and Organizer: Jayne Partridge

Moderator: A. A. Procassini

EVOLUTION OF A HIGH — RELIABILITY MOLDED DIP
R. Beard 72

HIGH — RELIABILITY CONSUMER IC'S
J. E. Feldt and E. R. Hnatek 78

ENVIRONMENTAL FACTORS GOVERNING FIELD RELIABILITY OF PLASTIC TRANSISTORS AND INTEGRATED CIRCUITS
B. Reich and E. B. Hakim 82

THE I. C. PLASTIC PACKAGE: A SIMPLE METHOD FOR PREDICTING PACKAGE PERFORMANCE
M. C. Halleck 88

RELIABILITY ASPECTS OF PLASTIC ENCAPSULATED INTEGRATED CIRCUITS
J. L. Flood 95

INTEGRATED CIRCUITS RELIABILITY — PLASTIC vs CERAMIC DIP'S
C. R. Gray 100

A RECOMMENDATION FOR CERAMIC OVER PLASTIC IC PACKAGES FOR 1972 REAL-TIME COMMERCIAL COMPUTER SYSTEMS
R. E. Sundius 102

Tutorial Failure Analysis Workshops and Clinics

Workshops Coordinator: P. H. Eisenberg

Workshop Subjects: P. H. Eisenberg and A. A. Tamburrino 105

INTERFACES

Chairman and Organizer: Harold Nigh

CHARGE — INDUCED INSTABILITIES IN 709 OPERATIONAL AMPLIFIERS
J. R. Haberer and J. J. Bart 106

A RELIABILITY STUDY OF INSULATED GATE FIELD EFFECT TRANSISTORS WITH AN $Al_2O_3SiO_2$ GATE STRUCTURE
E. E. Lampi and E. F. Labuda 112

DEGRADATION OF MNOS MEMORY TRANSISTOR CHARACTERISTICS AND FAILURE MECHANISM MODEL
M. H. Woods and J. W. Tuska 120

DEGRADATION ANYALSIS OF INFRARED AND VISIBLE OPTOELECTRONIC DEVICES
J. Lebailly, C. Gouin, and A. Desombre 126

THE EFFECTS OF DEVICE CONFIGURATION IN THE DEGRADATION OF GaP RED LIGHT EMITTING DIODES
R. L. Hartman and M. Kuhn 137

BONDING AND METALLIZATION

Chairman and Organizer: Jim Black

RELIABILITY IMPROVEMENT OF WIRE BONDS SUBJECTED TO FATIGUE STRESSES
K. V. Ravi and E. M. Philofsky 143

RELIABILITY OF MOLYBDENUM THIN FILMS IN HUMID ATMOSPHERES
A. Hornung 149

PURPLE PLAGUE AND GOLD PURITY
C. W. Horsting 155

A STATISTICAL MODEL FOR ELECTROMIGRATION – INDUCED FAILURE IN THIN FILM CONDUCTORS
J. D. Venables and R. G. Lye 159

EFFECTS OF COMPLEX ALLOY ADDITIONS ON ELECTROMIGRATION IN ALUMINUM FILMS
A. Gangulee and F. M. d'Heurle 165

"Electromigration in TiPdAu Conductors".
R. C. Pitetti 171

HYBRIDS, MULTI – LAYER BOARDS, AND PASSIVE COMPONENTS

Chairman and Organizer: John Seacord

THIN – FILM NICKEL – CHROMIUM RESISTOR FAILURES IN INTEGRATED CIRCUITS
V. C. Kapfer and J. J. Bart 175

FAILURE CHARACTERISTICS OF THIN – FILM CAPACITORS
J. S. Fisher 183

MULTI – LAYER – BOARD PLATED – THROUGH – HOLE FAILURE MECHANISMS
D. Grabbe 188

EDGE – CONNECTOR FAILURE MECHANISMS
W. J. Byrne 193

"Metallization Failures Caused by Organic Adhesives Used in Hybrid Microelectronic Devices".
R. S. Spriggs and A. H. Cronshagen 201

"High Temperature Reverse Bias Testing at Wafer Level".
G. H. Ebel 204

BIOGRAPHIES 208